

Title (en)
AQUEOUS STRIPPING AND CLEANING COMPOSITION

Title (de)
WÄSSRIGE STRIPP- UND REINIGUNGSZUSAMMENSETZUNG

Title (fr)
COMPOSITION AQUEUSE DE NETTOYAGE ET DE DESOXYDATION

Publication
EP 1470207 A1 20041027 (EN)

Application
EP 03729578 A 20030106

Priority
• US 0300291 W 20030106
• US 4261202 A 20020109

Abstract (en)
[origin: EP2281866A1] A composition for removing etch and/or ash residue or contaminants from a semiconductor substrate comprising: a. from 45 to 90 wt % of a water soluble organic solvent b. from 3 to 10 wt % of a sulfonic acid or its corresponding salt c. from 5 to 50 wt % water

IPC 1-7
C11D 1/62; **C23G 1/00**; **C23G 1/02**; **C03C 23/00**; **B08B 3/00**; **B08B 3/12**; **B08B 6/00**; **C11D 11/00**; **G03F 7/42**; **H05K 3/26**; **C11D 3/43**; **C11D 7/50**; **C11D 1/22**; **C11D 1/14**; **C11D 3/34**; **C11D 7/34**

IPC 8 full level
B08B 3/08 (2006.01); **C09D 9/00** (2006.01); **C11D 1/14** (2006.01); **C11D 1/22** (2006.01); **C11D 3/34** (2006.01); **C11D 3/43** (2006.01); **C11D 7/26** (2006.01); **C11D 7/32** (2006.01); **C11D 7/34** (2006.01); **C11D 7/50** (2006.01); **C11D 11/00** (2006.01); **C23G 5/02** (2006.01); **G03F 7/42** (2006.01); **H01L 21/02** (2006.01); **H01L 21/3213** (2006.01); **H05K 3/26** (2006.01)

CPC (source: EP KR US)
B08B 3/08 (2013.01 - EP US); **C09D 9/00** (2013.01 - EP US); **C11D 1/143** (2013.01 - EP US); **C11D 1/22** (2013.01 - EP US); **C11D 1/62** (2013.01 - KR); **C11D 3/3409** (2013.01 - EP US); **C11D 3/3418** (2013.01 - EP US); **C11D 3/43** (2013.01 - EP US); **C11D 7/265** (2013.01 - EP US); **C11D 7/3218** (2013.01 - EP US); **C11D 7/3263** (2013.01 - EP US); **C11D 7/3281** (2013.01 - EP US); **C11D 7/34** (2013.01 - EP US); **C11D 7/5004** (2013.01 - EP US); **C23G 5/02** (2013.01 - EP US); **G03F 7/426** (2013.01 - EP US); **H01L 21/02071** (2013.01 - EP US); **C11D 2111/22** (2024.01 - EP US); **Y10S 134/902** (2013.01 - EP US)

Designated contracting state (EPC)
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PT SE SI SK TR

DOCDB simple family (publication)
EP 2281866 A1 20110209; AT E517974 T1 20110815; AU 2003216037 A1 20030730; CN 1298827 C 20070207; CN 1612927 A 20050504; CN 1900829 A 20070124; EP 1470207 A1 20041027; EP 1470207 A4 20050316; EP 1470207 B1 20110727; HK 1078102 A1 20060303; JP 2006505629 A 20060216; JP 2009102729 A 20090514; KR 100714951 B1 20070504; KR 20040075058 A 20040826; MY 130394 A 20070629; TW 200306464 A 20031116; TW I300885 B 20080911; US 2003130146 A1 20030710; US 2005217697 A1 20051006; US 6943142 B2 20050913; US 8231733 B2 20120731; WO 03060045 A1 20030724

DOCDB simple family (application)
EP 10075679 A 20030106; AT 03729578 T 20030106; AU 2003216037 A 20030106; CN 03802036 A 20030106; CN 200610105651 A 20030106; EP 03729578 A 20030106; HK 05109634 A 20051028; JP 2003560132 A 20030106; JP 2008238167 A 20080917; KR 20047010655 A 20030106; MY PI20030057 A 20030108; TW 92100282 A 20030108; US 0300291 W 20030106; US 13995005 A 20050527; US 4261202 A 20020109